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CT2630, CT2631

8-Pin DMC-Isolator®

10Mbit/s High Speed Logic Gate Optocoupler

Features

- High speed 10Mbit/s
- High isolation voltage between input and output (Viso=5000 Vrms)
- Patented coplanar structure DMC-Isolator®
- Operating temperature range -55°C to 110°C
- RoHS and REACH compliance
- Halogen Free compliance
- MSL class 1
- Regulatory Approvals
  - ✓ UL - UL1577 (E364000)
  - ✓ VDE - EN60747-5-5(VDE0884-5)
  - ✓ CQC – GB4943.1, GB8898(14001104779)
  - ✓ IEC62368 (FI/41119)

Description

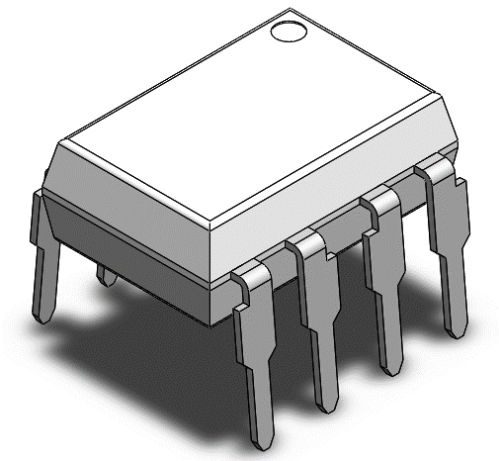
The CT2630, CT2631, devices each consist of an infrared emitting diode, optically coupled to a very high speed integrated photo-detector logic gate with a strobable output. This output features an open collector,there by permitting wired OR outputs.

The devices are packaged in an 8-pin DIP DMC-Isolator® package and also available in gullwing (400mil) and surface mount lead forming.

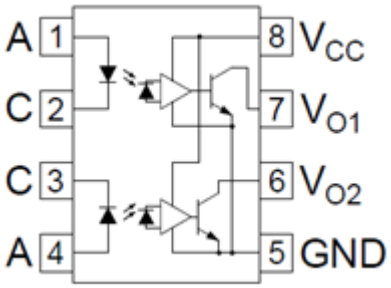
Applications

- Line receivers
- Telecommunication equipment
- High speed logic ground isolation
- Feedback loop in switch-mode power supplies
- Home appliances

Package Outline



Schematic



Truth Table

(POSITIVE LOGIC)	
Input	**Output**
L	H
H	L

Note: Different lead forming options available. See package dimension.

Absolute Maximum Ratings T_A = 25°C, unless otherwise specified

Stresses in excess of the absolute maximum ratings can cause permanent damage to the device. Functional operation of the device is not implied at these or any other conditions in excess of those given in the operational sections of this document. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameters	Ratings	Units	Notes
V_{ISO}	Isolation voltage (AC, 1 minute, 40 ~ 60% R.H.)	5000	V_{RMS}	
T_{OPR}	Operating temperature	-55 ~ +110	°C	
T_{STG}	Storage temperature	-55 ~ +150	°C	
T_{SOL}	Soldering temperature (For 10 seconds)	260	°C	
Emitter				
I_F	Forward current	25	mA	
V_R	Reverse voltage	6	V	
P_D	Power dissipation	40	mW	
Detector				
P_D	Power dissipation	85	mW	
I_O	Average Output current	50	mA	
V_{CC}	Supply voltage	7	V	
V_O	Output voltage	7	V	

Electrical Characteristics *TA =-40 - 85°C (unless otherwise specified). Typical values are measured at TA = 250C and VCC=5V*

Emitter Characteristics

Symbol	*Parameters*	*Test Conditions*	*Min*	*Typ*	*Max*	*Units*	*Notes*
V_F	Forward voltage	I_F = 10mA	-	1.6	1.8	V	
V_R	Reverse Voltage	I_R = 5μA	5.0	-	-	V	
$\Delta V_F/\Delta T_A$	Temperature coefficient of forward voltage	I_F =10mA	-	-1.6	-	mV/°C	

Detector Characteristics

Symbol	*Parameters*	*Test Conditions*	*Min*	*Typ*	*Max*	*Units*	*Notes*
I_{CCL}	Logic Low Supply Current	I_F=10mA, V_O=Open, V_{CC}=5.5V	-	15	20	mA	1
		I_{F1}=I_{F2}=10mA,V_O=Open,V_{CC}=5.5V			25		2
I_{CCH}	Logic High Supply Current	I_F=0mA, V_O=Open, V_{CC}=5.5V	-	13	15	mA	

Transfer Characteristics

Symbol	*Parameters*	*Test Conditions*	*Min*	*Typ*	*Max*	*Units*	*Notes*
I_{OH}	Logic High Output Current	I_F=250uA, V_O= 5.5V,		2	100	uA	
I_{FT}	Input Threshold Current	V_{CC}=5.5V, V_O=0.6V, I_O=13mA	-	3.3	5	mA	
V_{OL}	Logic Low Output Voltage	I_F=5mA, I_O=13mA, V_{CC}=5.5V,	-	0.35	0.6	V	

Notes

1. Single Channel
2. Dual Channel

Electrical Characteristics *TA =-40 - 85°C (unless otherwise specified). Typical values are measured at TA = 250C and VCC=5V*

Switching Characteristics

Symbol	*Parameters*		*Test Conditions*	*Min*	*Typ*	*Max*	*Units*	*Notes*
T_{PHL}	Propagation Delay Time Logic High to Logic Low		C_L=15pF,R_L=350Ω	-	42	75	ns	
T_{PLH}	Propagation Delay Time Logic Low to Logic High			-	38	75	ns	
P_{WD}	Pulse Width Distortion			-	5	34	ns	
Tr	Output Rise Time			-	40	-	ns	
Tf	Output Fall Time			-	10	-	ns	
CM_H	Common Mode Transient Immunity at Logic Low	CT2630	I_F = 0mA , V_{OH}=2.0V, R_L=350Ω, TA=25°C, V_{CM}=10Vp-p	-	-	-	V/μs	
		CT2631	I_F = 0mA , V_{OH}=2.0V, R_L=350Ω, TA=25°C, V_{CM}=50Vp-p	5000	-	-		
CM_L	Common Mode Transient Immunity at Logic High	CT2630	I_F = 7.5mA , V_{OL}=0.8V, R_L=350Ω, TA=25°C, V_{CM}=10Vp-p	-	-	-	V/μs	
		CT2631	I_F = 7.5mA , V_{OL}=0.8V, R_L=350Ω, TA=25°C, V_{CM}=50Vp-p	5000	-	-		

Typical Characteristic Curves *T_A = 25°C, unless otherwise specified*

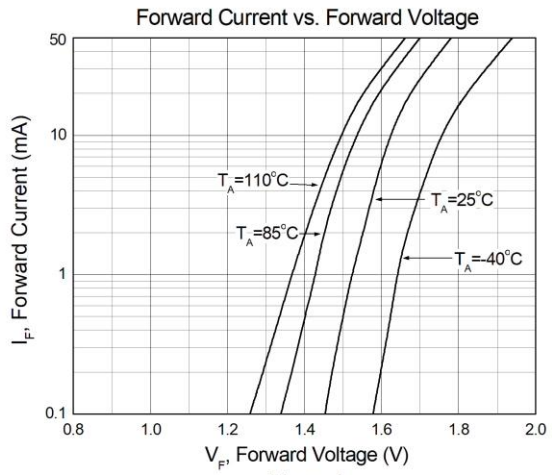


Figure 1

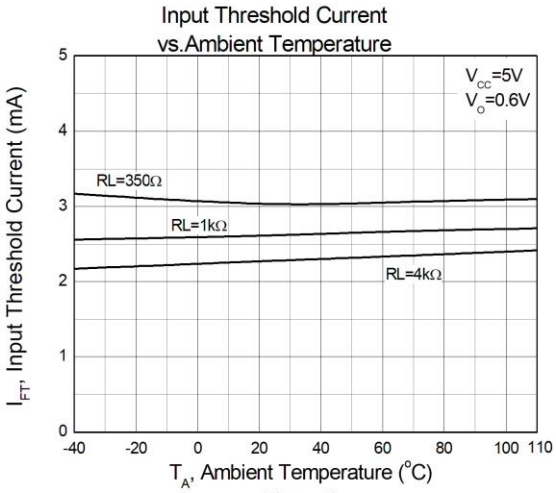


Figure 2

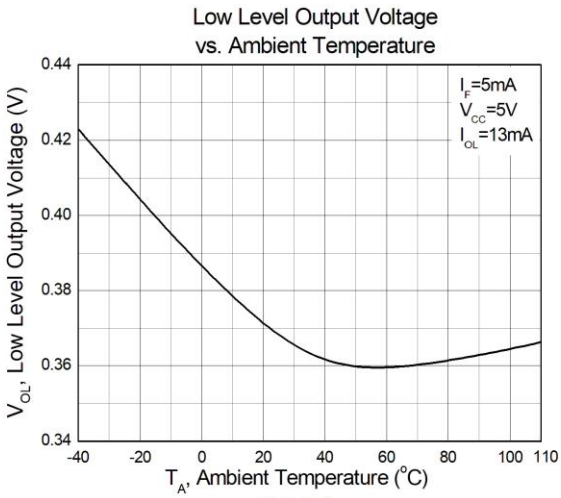


Figure 3

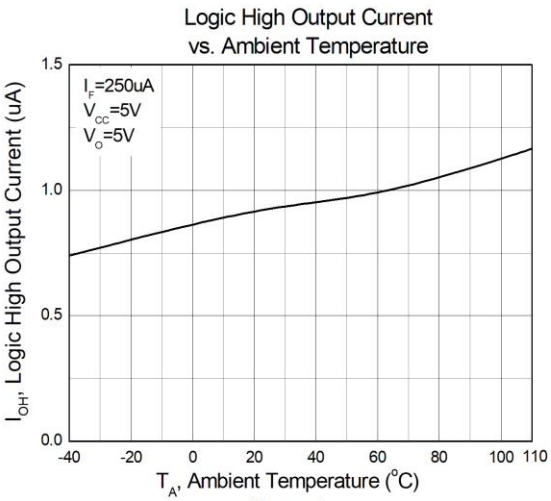


Figure 4

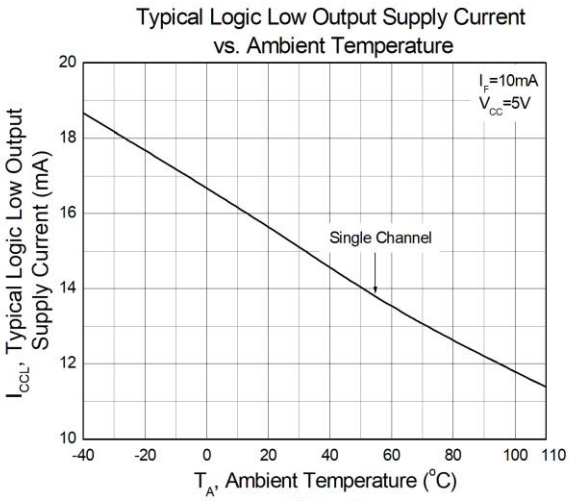


Figure 5

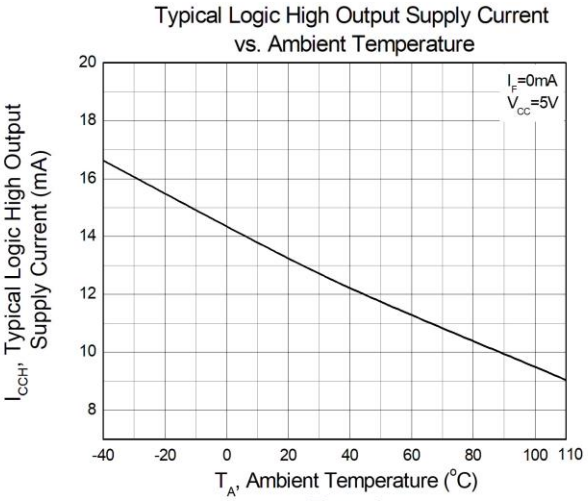


Figure 6

Typical Characteristic Curves *T_A = 25°C, unless otherwise specified*

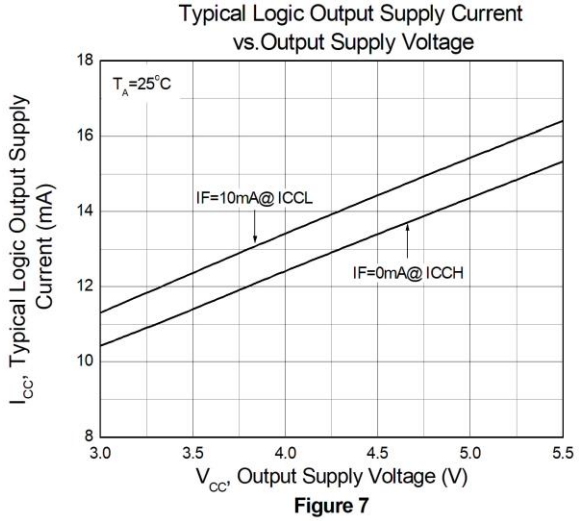


Figure 7

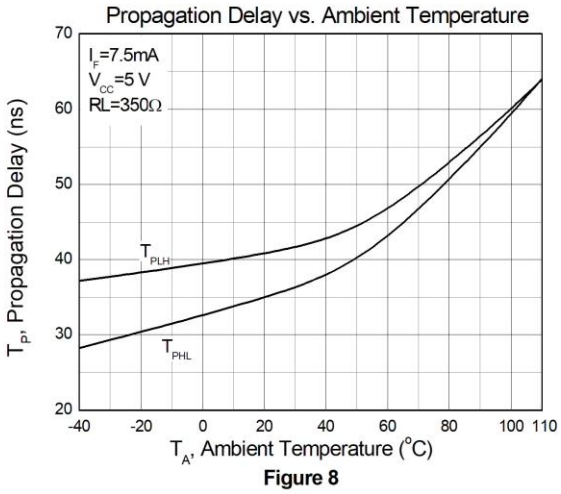


Figure 8

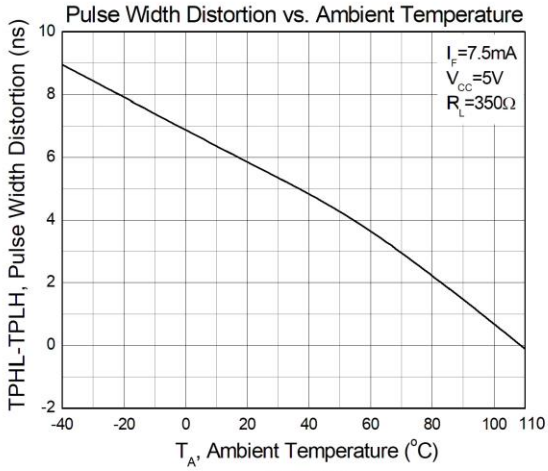


Figure 9

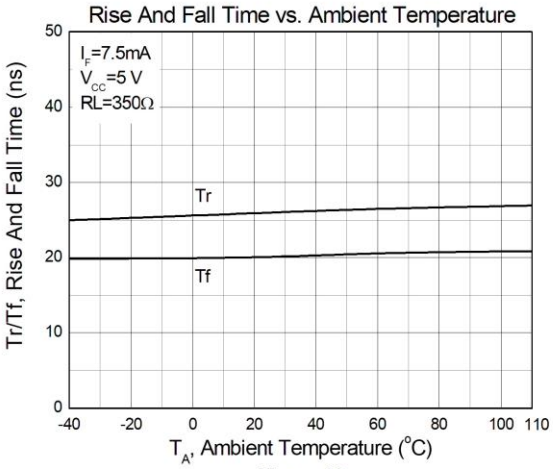


Figure 10

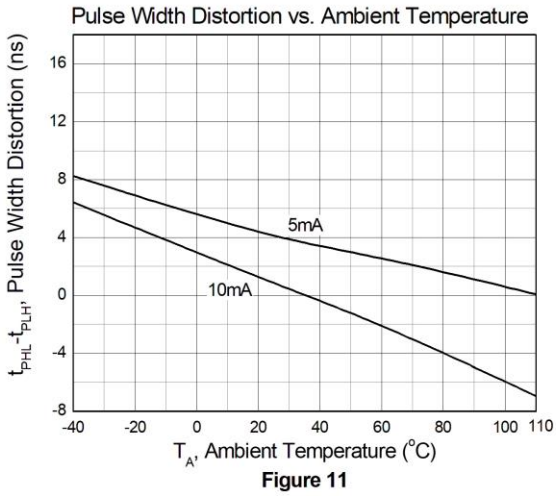


Figure 11

Test Circuits

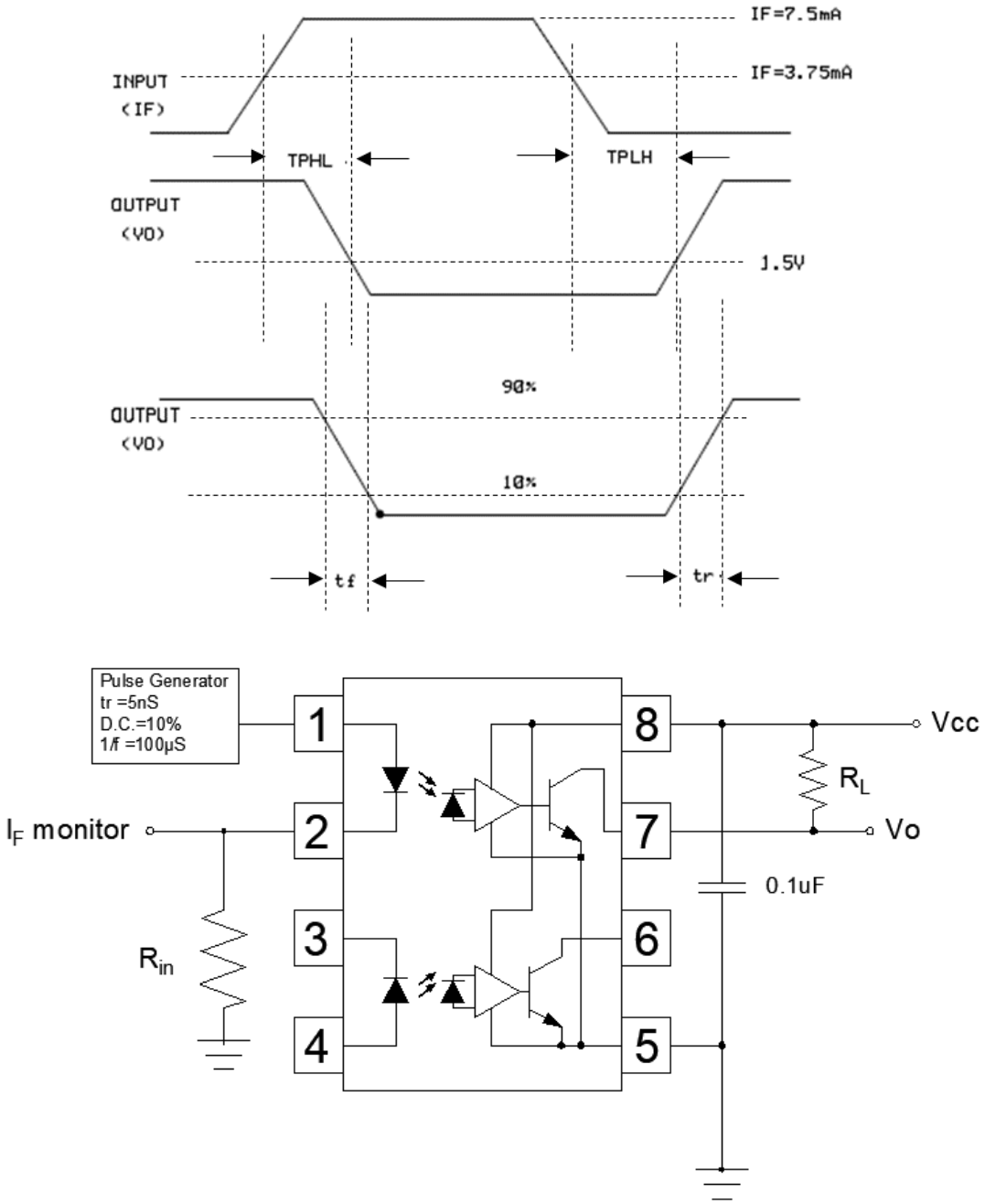


Figure 12: Switching Time Test Circuits

Test Circuits

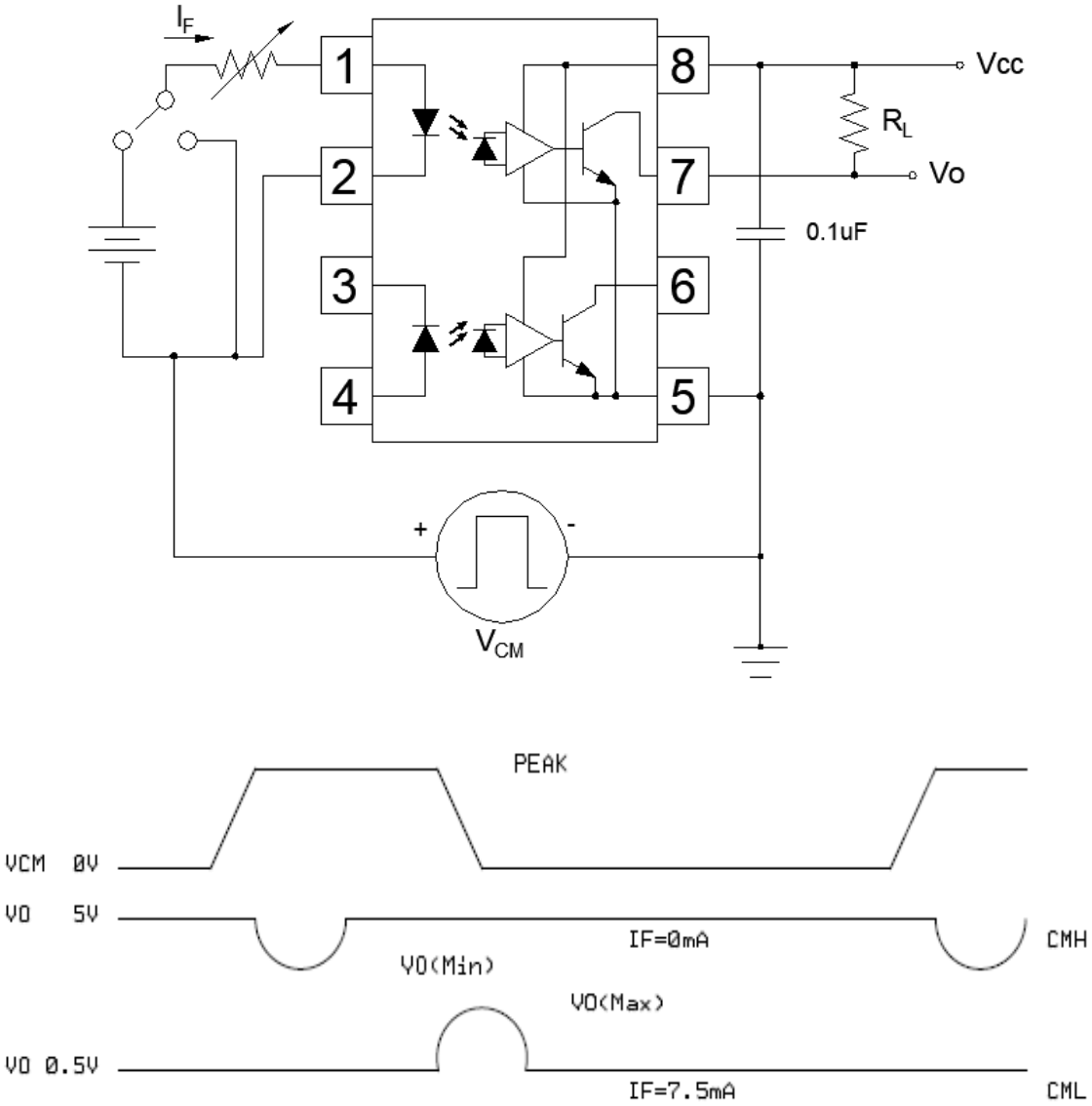
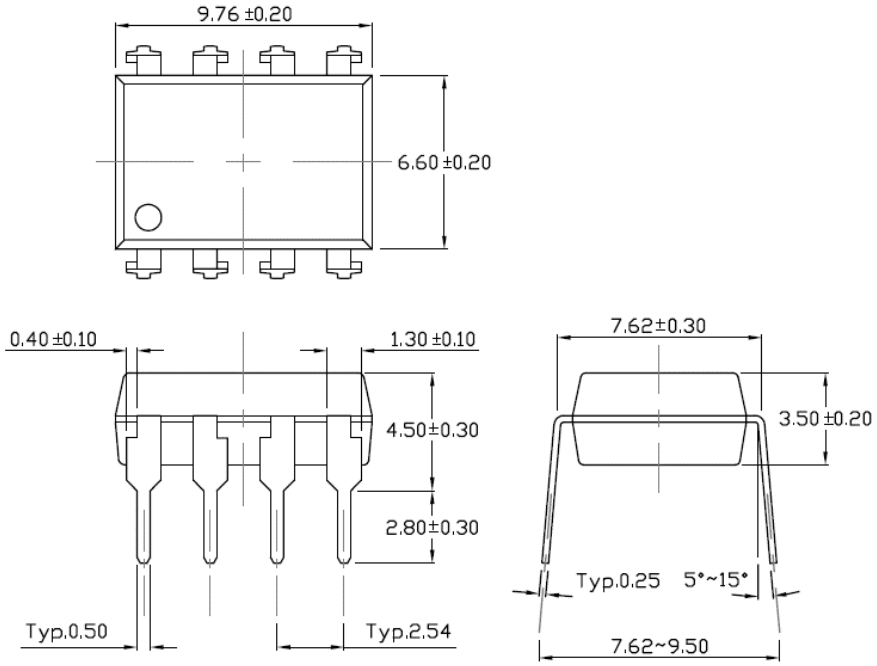


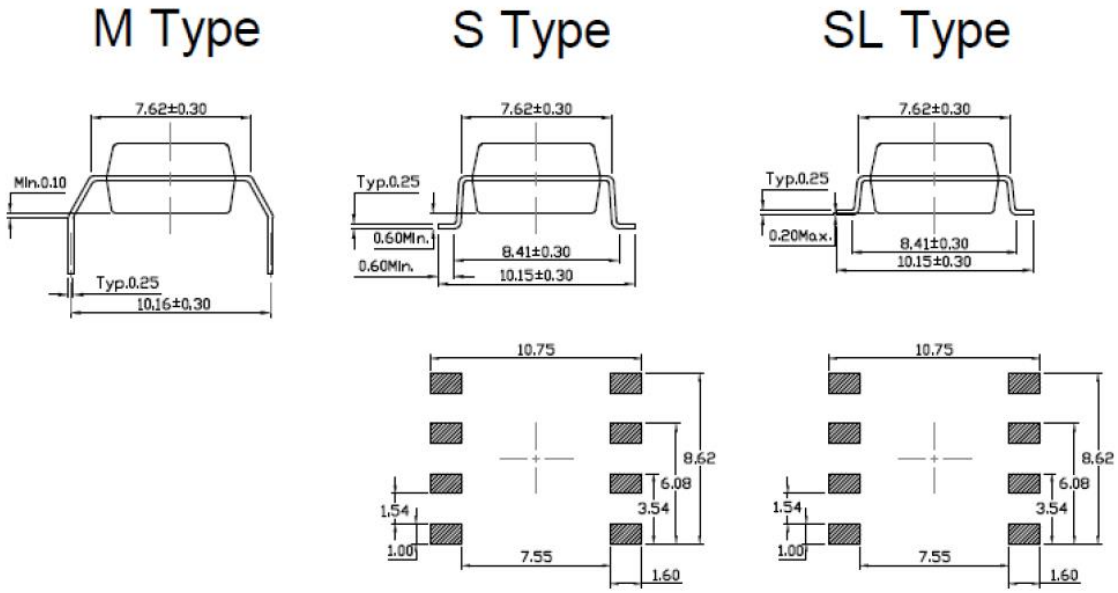
Figure 13: CMR Test Circuits

Package Dimension *Dimensions in mm unless otherwise stated*

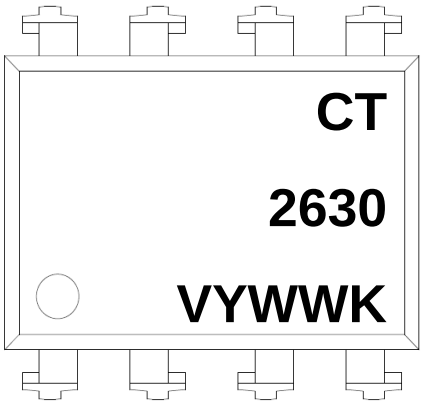
Standard DIP – Through Hole



Forming Option



Marking Information



Note:

CT : Denotes “CT Micro”
2630 : Part Number
V : VDE Safety Mark Option (Blank or V)
Y : One Digit Year Code
WW : Two Digit Work Week
K : Manufacturing Code

Ordering Information

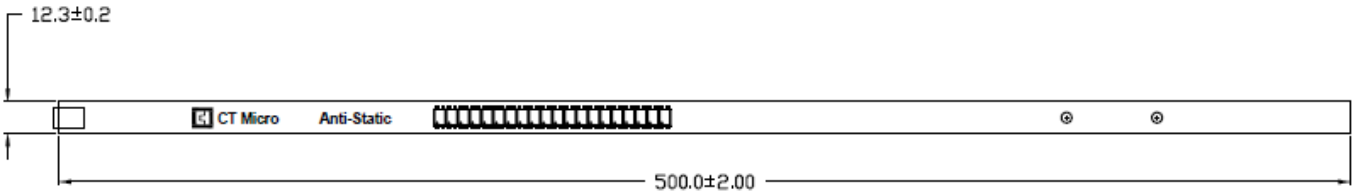
CT263X (V)(Y)(Z)

CT = Denotes “CT Micro”
263X = Part Number
X = Part No. (0 or 1)
V = VDE Safety Mark Option (Blank or V)
Y = Lead Form Option (Blank, S, SL or M)
Z = Tape and Reel Option (Blank, T1 or T2)

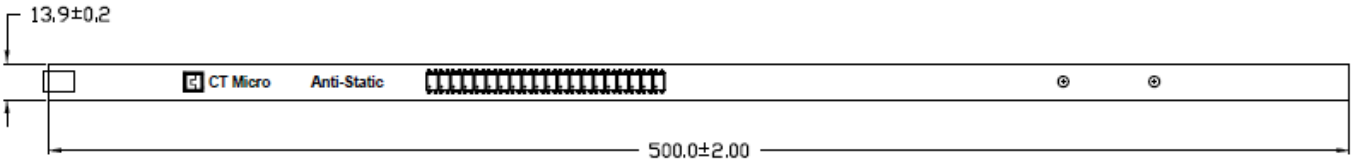
Option	***Description***	***Quantity***
None	Standard 8 Pin Dip	40 Units/Tube
M	Gullwing (400mil) Lead Forming	40 Units/Tube
S(T1)	Surface Mount Lead Forming – With Option 1 Taping	1000 Units/Reel
S(T2)	Surface Mount Lead Forming – With Option 2 Taping	1000 Units/Reel
SL(T1)	Surface Mount (Low Profile) Lead Forming– With Option 1 Taping	1000 Units/Reel
SL(T2)	Surface Mount (Low Profile) Lead Forming– With Option 2 Taping	1000 Units/Reel

Carrier Specifications *Dimensions in mm unless otherwise stated*

Tube Option Standard DIP

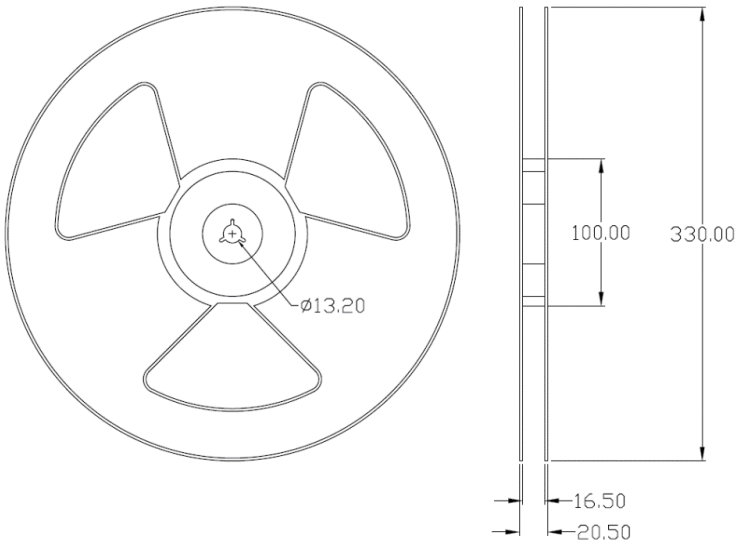


Tube Option M Type



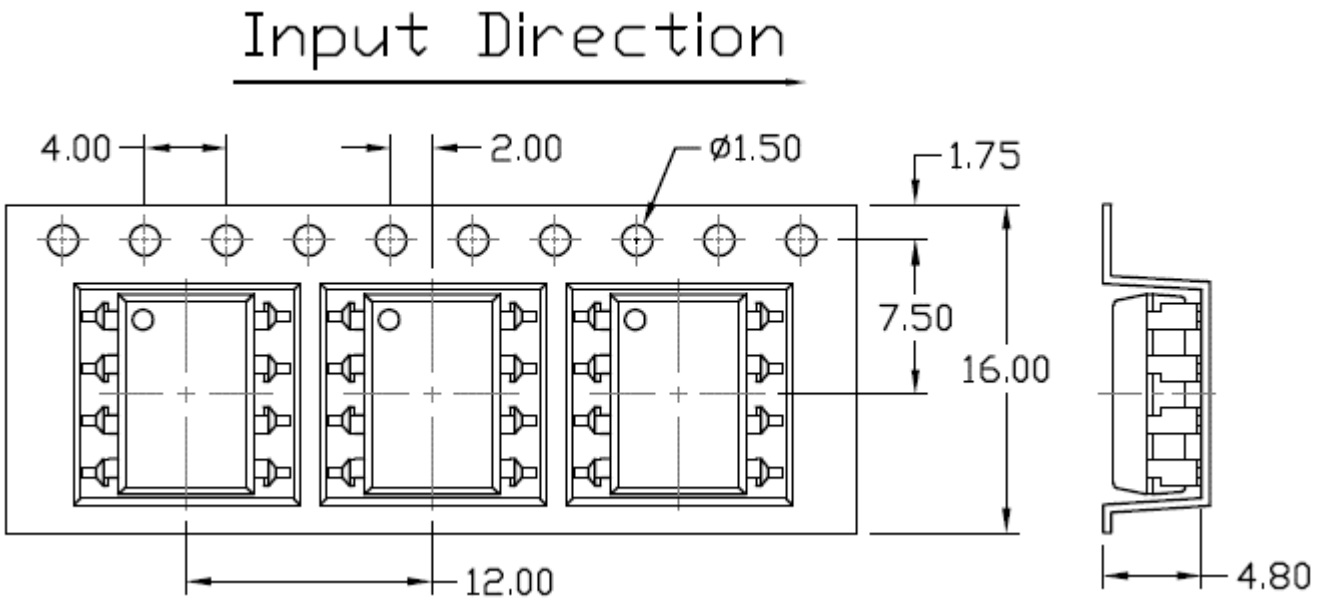
Reel Dimension *All dimensions are in mm, unless otherwise stated*

Option S(T1/T2) & SL(T1/T2)

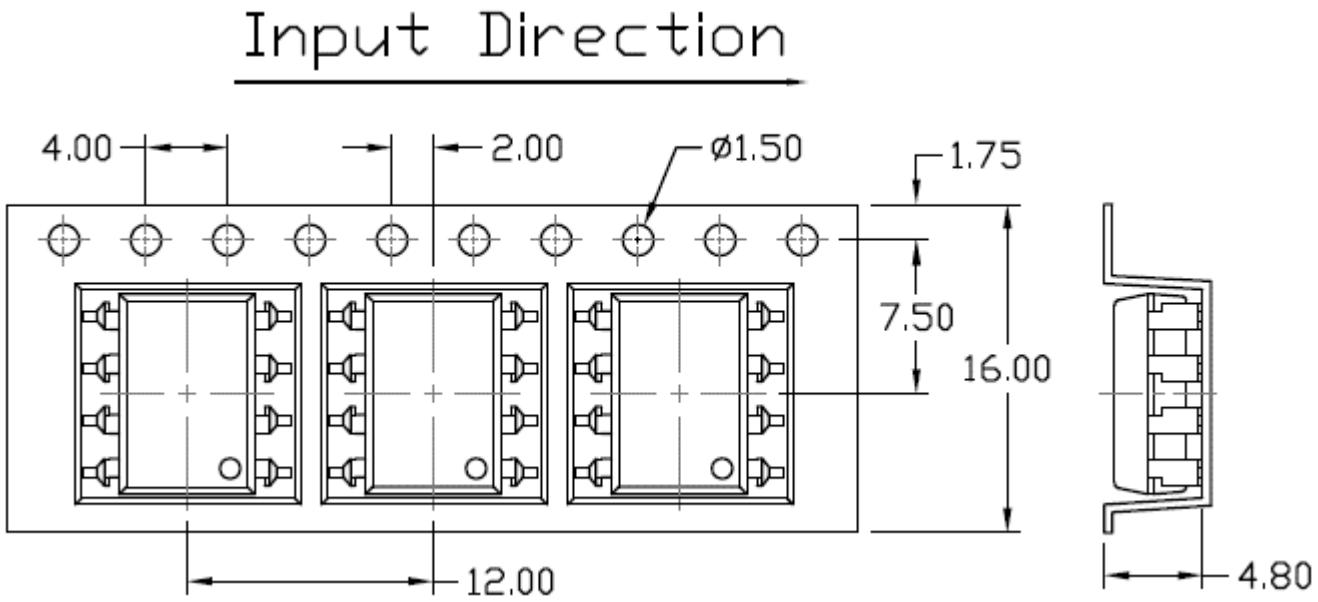


Carrier Tape Specifications *Dimensions in mm unless otherwise stated*

Option S(T1) & SL(T1)



Option S(T2) & SL(T2)



Solderability spec (Follow the JEDEC standard JESD22-B102)

Reflow Soldering: Immersed surface, other than the end of pin as cut-surface, must be covered by solder.

Solder-Bath: More than 95% of the electrode must be covered with solder.

Wave soldering (Follow the JEDEC standard JESD22-A111)

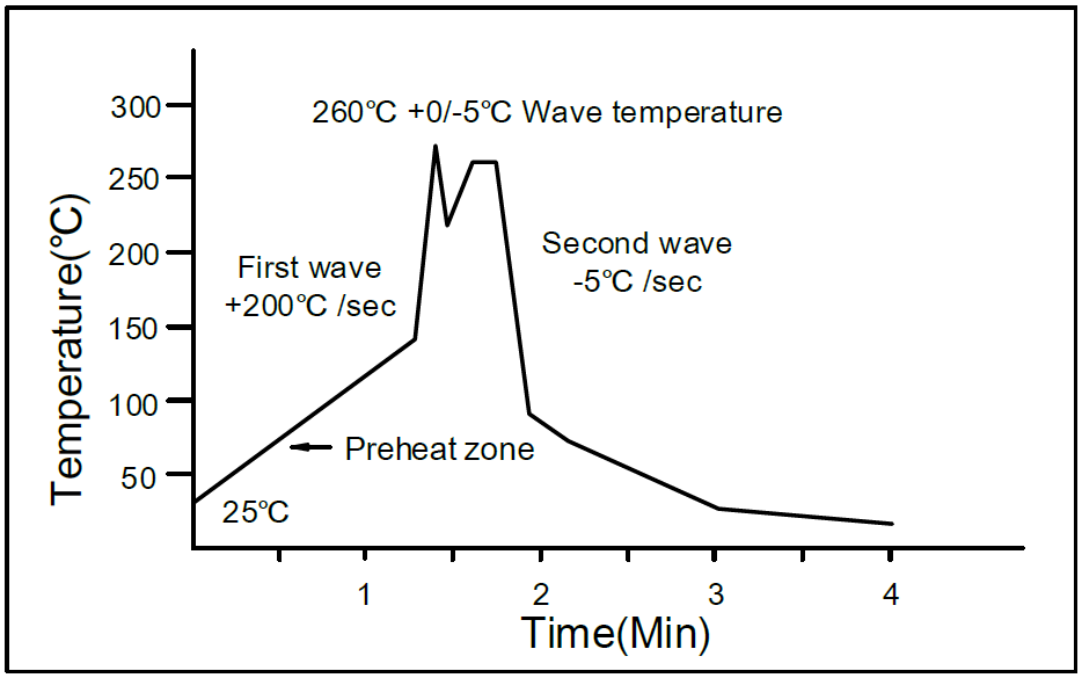
One time soldering is recommended within the condition of temperature.

Temperature: 260+0/-5˚C.

Time: 10 sec.

Preheat temperature: 25 to 140˚C.

Preheat time: 30 to 80 sec.



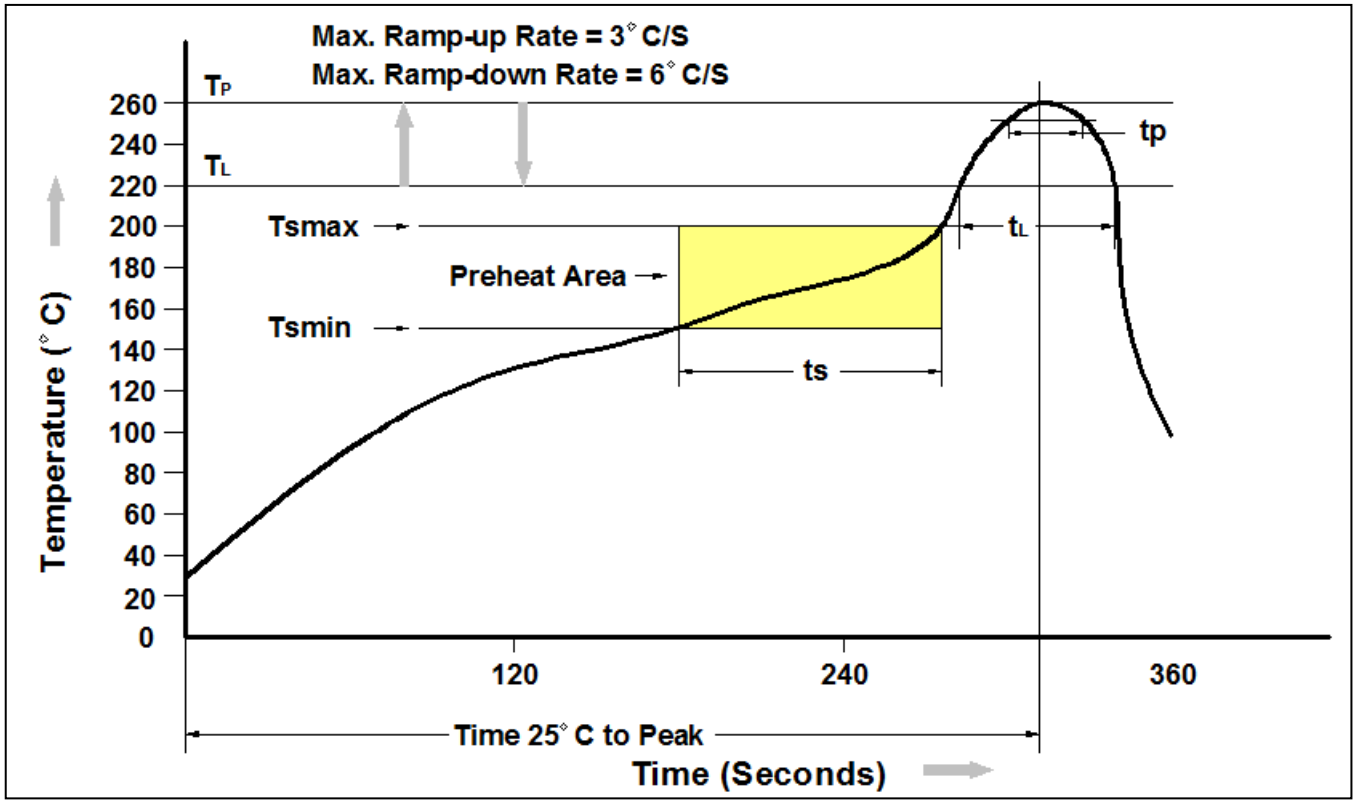
Iron soldering (Follow the standard MIL-STD 202G, Method 210F)

Allow single lead soldering in every single process.

One time soldering is recommended. Temperature: 350±10˚C

Time: 5 sec max.

Reflow Profile (Follow the JEDEC standard J-STD-020)



Profile Feature	Pb-Free Assembly Profile
Temperature Min. (Tsmin)	150°C
Temperature Max. (Tsmax)	200°C
Time (ts) from (Tsmin to Tsmax)	60-120 seconds
Ramp-up Rate (t_L to t_P)	3°C/second max.
Liquidous Temperature (T_L)	217°C
Time (t_L) Maintained Above (T_L)	60 – 150 seconds
Peak Body Package Temperature	260°C +0°C / -5°C
Time (t_P) within 5°C of 260°C	30 seconds
Ramp-down Rate (T_P to T_L)	6°C/second max
Time 25°C to Peak Temperature	8 minutes max.

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2. *A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.*